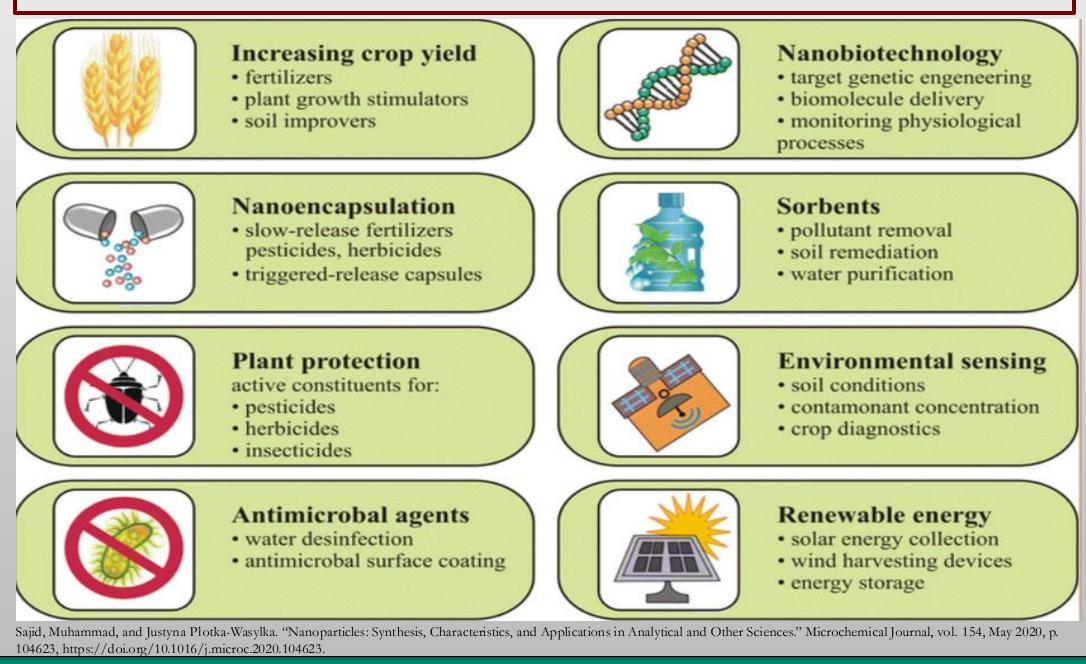
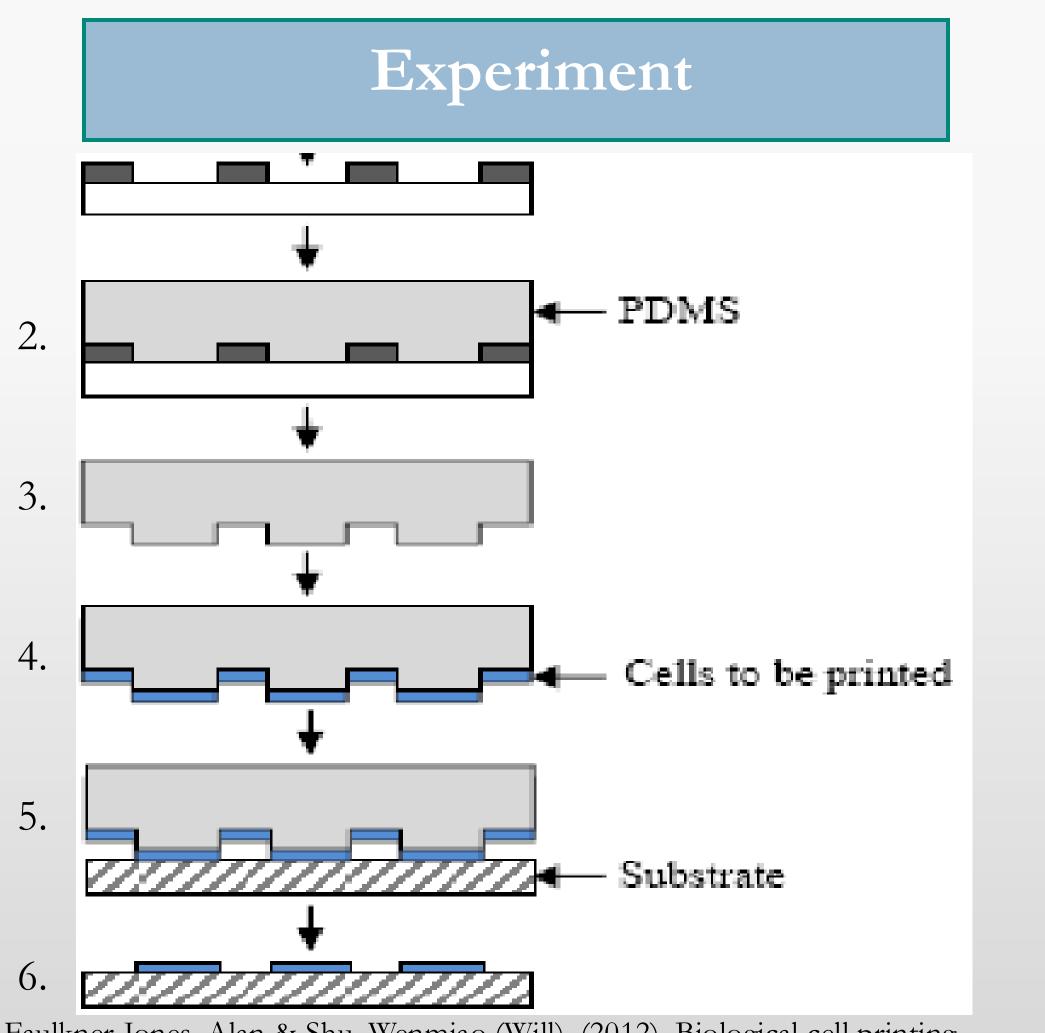


Introduction

Microcontact printing (µCP) is a technique rooted in soft lithography (the process of creating a relief pattern on a substrate using an elastomeric stamp) and has a multitude of applications. Soft lithography is widely used n microfluidics, microelectronics, and biotechnology for creating microarray technology. The patterned elastomeric stamp used in the process of microcontact printing (µCP) transfers ink such as proteins, polymers, or nanoparticles to the surface of a substrate allowing for the examination of how molecules react on a specific surface. A few different processes of microcontact printing (µCP) are decomposition of metals by chemical vapor deposition, electroplating, electroless plating, protein microarrays, and substrates that are capable of analyzing antigen antibody interactions (antigen antibody interactions are interactions between protective proteins replicated by the immune system (antibodies) and their attachment to bacteria, fungi, & viruses (antigens)). Some of the fields microcontact printing (µCP) is used for:



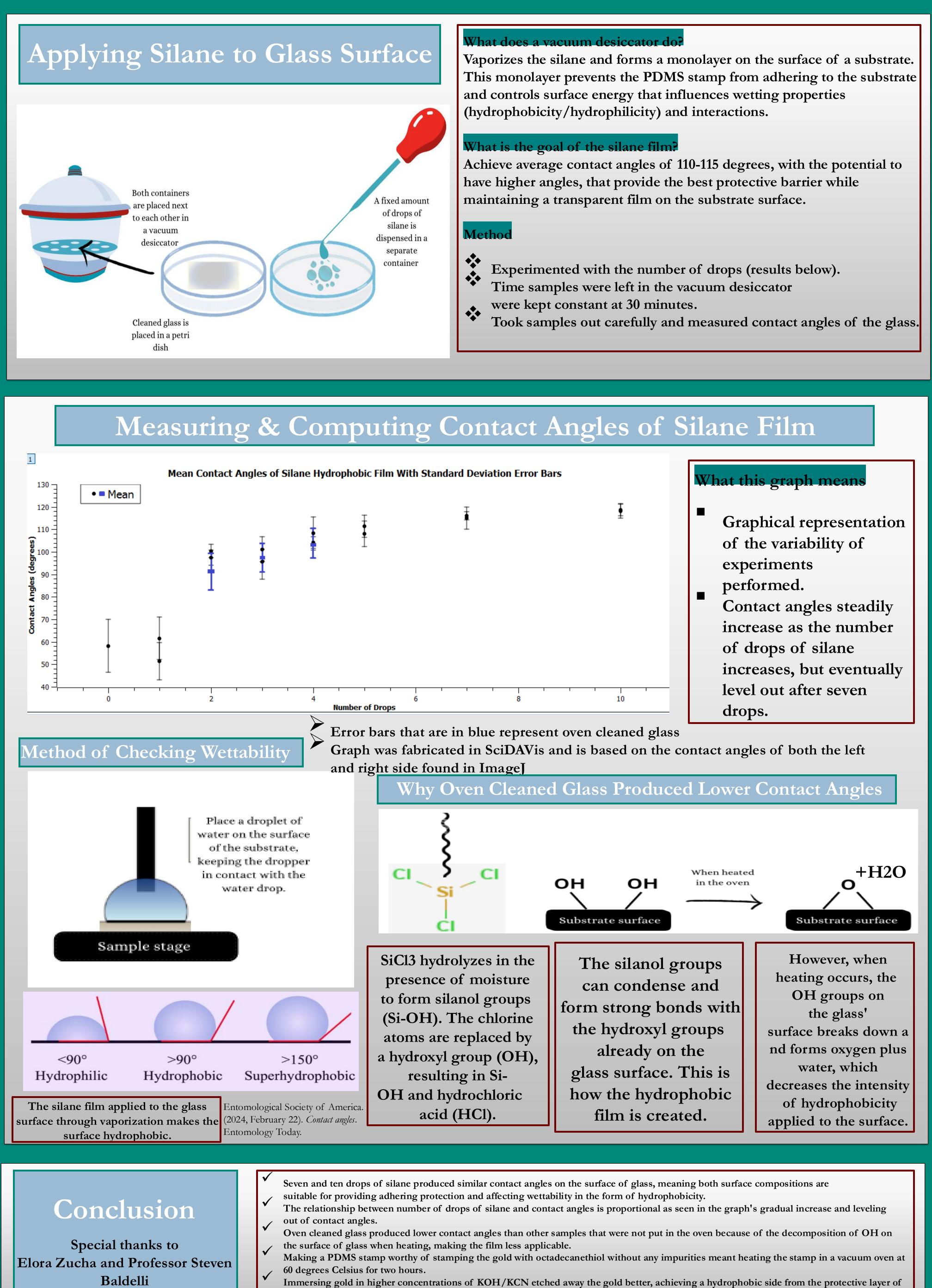


Faulkner-Jones, Alan & Shu, Wenmiao (Will). (2012). Biological cell printing technologies. Nanotechnology Perceptions. 8. 35-57. 10.4024/N02FA12A.ntp.08.01.

- Trichloroperfluorooctyl silane is applied to the surface of a substrate through the use of a vacuum desiccator A polydimethylsiloxane (PDMS) stamp is made and poured
- over substrate
- Cured stamp is peeled away from substrate, forming a relief pattern from the patterned silane hydrophobic film
- Octadecanethiol (ODT) is doused onto stamp, known as "inking", and dried with a stream of nitrogen gas
- The octadecanethiol (ODT) cells are pressed onto gold for a fixed amount of time
- When the stamp is removed from the gold, self-assembled monolayers (SAMs) are left behind
- Bare gold from the area where the stamp did not make contact with the gold is etched away in a solution of KOH and KCN

Microcontact Printing (µCP) Maddison Coca and Prof. Steven Baldelli

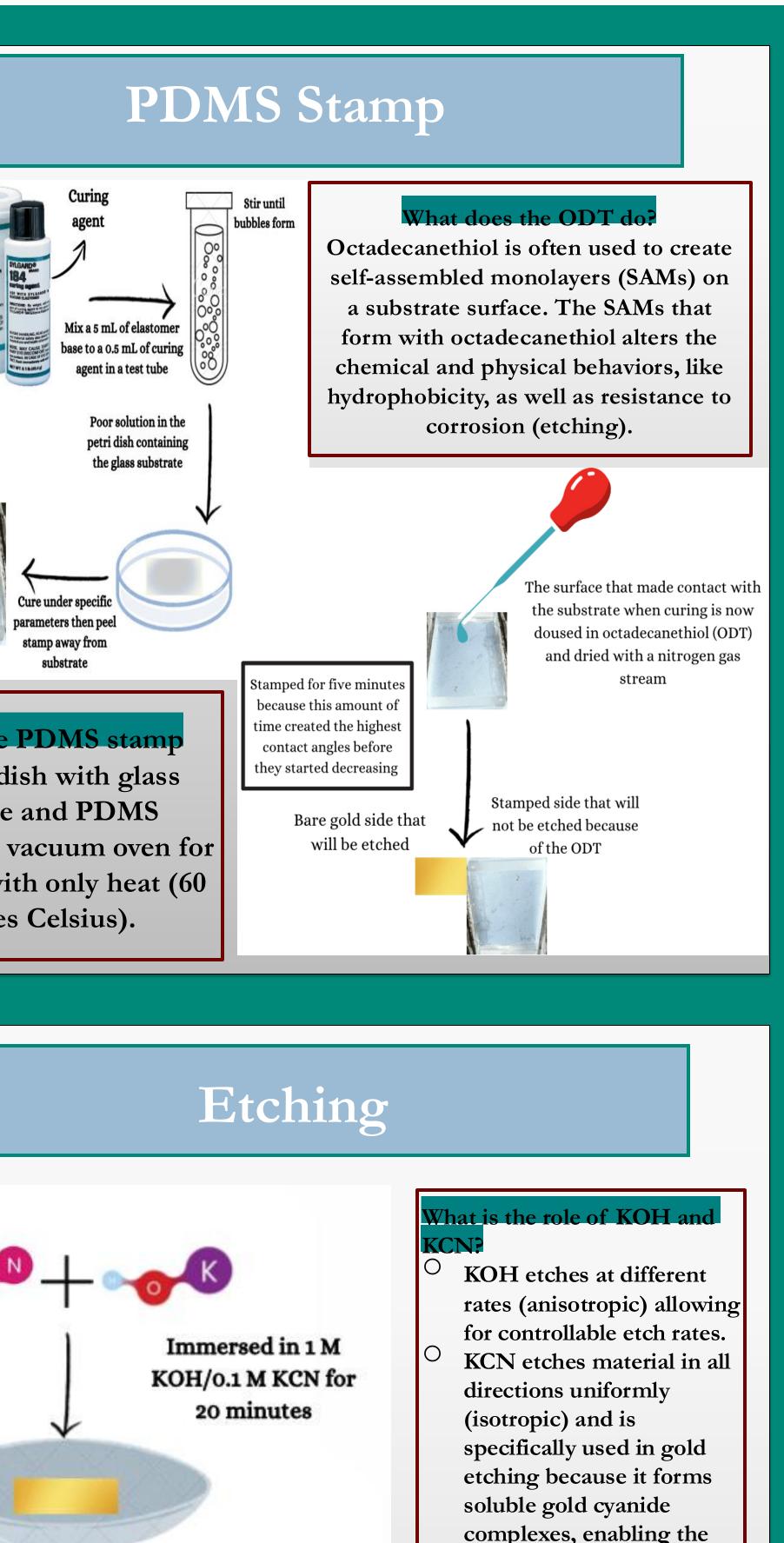
Department of Chemistry, University of Houston, Houston, Texas



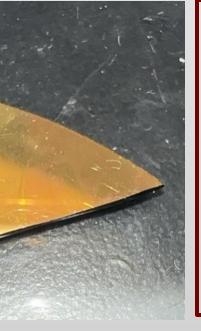
octadecanethiol and a hydrophilic side from the corrosion of bare gold without octadecanethiol

SIlicone elastomer base
Stamp is now ready for replicating the substrate's surface pattern
Curing the Put petri d substrate solution in a two hours we degree
KC
Left: 100.1 degrees &



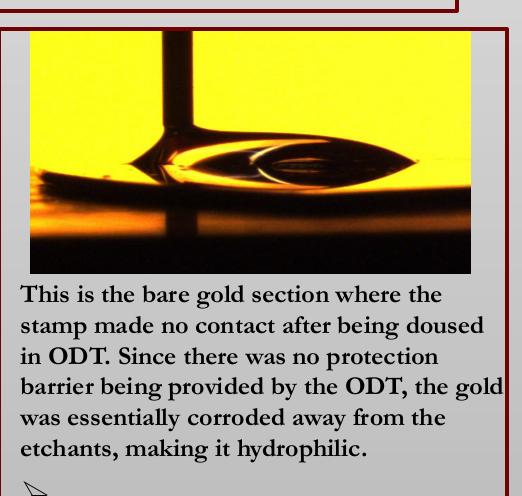


Results



On the left side is where the PDMS stamp made contact with the gold and on the right side is where the PDMS stamp did not make contact with the gold, allowing KOH/KCN to etch away the bare gold.

This is the stamped part of the gold. The OD T acted as a wet-etch protection making the gold in this area stay Right: 97.0 degrees hydrophobic.



gold to dissolve.

Left: 41.6 degrees & Right: 48.1 degrees